



Series APF Low Height Thin Fin Forged Heat Sinks

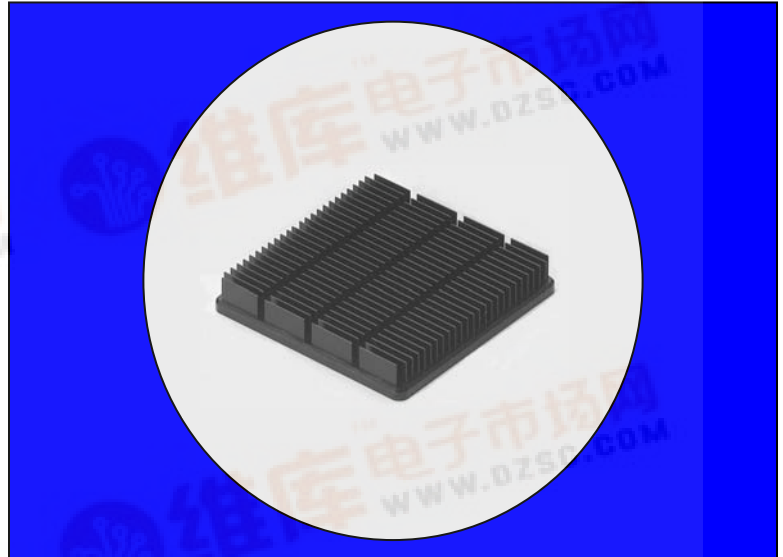
Technical Data

Features

- Precision Forging Technology for High Power Applications
- Low Profile Thin Fins
- Designed for BGA and Other Surface Mount Packages
- Select from Multiple Fin Heights
- Improved Thermal Performance Over Conventional Heat Sinks

Product Benefits

- No Special Tools Needed for Assembly
- No Additional Holes Required On the PCB
- Adhesive Tape Mounting Convenience



Series APF Low Height Thin Fin Forged Heat Sink				
Part Number	Fin Matrix (Rows x Columns)	Length x Width x Height (mm)	Thermal Resistance (°C/Watt @ 200 LFPM)	Pressure Drop (Inches of Water)
APF19-19-06CB	12 X 2	19 x 19 x 6.3	7.05	.033
APF19-19-10CB	12 X 2	19 x 19 x 9.5	5.25	.033
APF19-19-13CB	12 X 2	19 x 19 x 12.7	3.95	.033
APF30-30-06CB	19 x 3	30 x 30 x 6.3	4.35	.039
APF30-30-10CB	19 x 3	30 x 30 x 9.5	3.25	.039
APF30-30-13CB	19 x 3	30 x 30 x 12.7	2.45	.039
APF40-40-06CB	26 x 4	40 x 40 x 6.3	3.30	.043
APF40-40-10CB	26 x 4	40 x 40 x 9.5	2.50	.043
APF40-40-13CB	26 x 4	40 x 40 x 12.7	1.90	.043

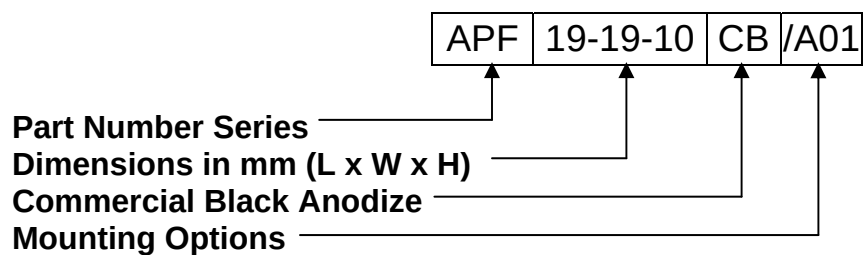
TAPE STYLES

Material: Nylon Plastic per UL94-V0

Thermal Tape	Supplier	Thickness (mm)	Thermal Impedance (°C-in²/W)	Dielectric Strength (V/mil)	Description
A01	IERC	0.13	0.82	4,000	Double-sided acrylic adhesive on a Kapton MT carrier.
T410	Chomerics	0.18	1.10	N/A	Double-sided acrylic adhesive loaded w/aluminum oxide on an aluminum foil carrier.
T411	Chomerics	0.28	1.00	N/A	Double-sided silicone adhesive with expanded aluminum mesh carrier.
T412	Chomerics	0.23	0.25	N/A	Double-sided acrylic adhesive loaded w/titanium diboride on an expanded aluminum carrier.



HOW TO ORDER?



Adhesive

Double-sided Kapton®

“/A01”

Chomerics Thermattach®

“T410, T411, or T412”

Example: APF19-19-10CB/A01